



THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Keith E. FOGEL et al. CONFIRM. NO.: 6557
SERIAL NO.: 10/815,103 ART UNIT: 2826
FILED: 03/31/2004 EXAMINER: L. ANDUJAR
TITLE: INTERCONNECTIONS FOR FLIP-CHIP USING LEAD-FREE
SOLDERS AND HAVING REACTION BARRIER LAYERS

ATTORNEY DOCKET NO.: YOR920030190US1

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT UNDER 37 C.F.R. §1.116

Sir:

Responsive to the final Office Action of October 3, 2007, please reconsider and allow this application in view of the following:

Amendments to the Specification	Page	2
Listing of and Amendments to Claims	Page	3
Remarks	Page	7

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

January 3, 2008

Date

Daniel J. Horan
Name of Person Making Deposit